

LNPTM THERMOCOMPTM COMPOUND GF006

GF-1006 REGION AMERICAS

DESCRIPTION

LNP THERMOCOMP GF006 compound is based on Polysulfone (PSU) resin containing 30% glass fiber.

GENERAL INFORMATION	
Features	High stiffness/Strength, High temperature resistance, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polysulfone (PSU)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Building and Construction	Building Component
Consumer	Personal Accessory
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL (1)			
Tensile Stress, break	104	MPa	ASTM D638
Tensile Strain, break	2	%	ASTM D638
Tensile Modulus, 50 mm/min	8820	MPa	ASTM D638
Flexural Stress	156	MPa	ASTM D790
Flexural modulus	8270	MPa	ASTM D790
Tensile Stress, break	100	MPa	ISO 527
Tensile Strain, break	1.9	%	ISO 527
Tensile Modulus, 1 mm/min	8420	MPa	ISO 527
Flexural Stress	150	MPa	ISO 178
Flexural Modulus	8390	MPa	ISO 178
IMPACT (1)			
Izod Impact, unnotched, 23°C	421	J/m	ASTM D4812
Izod Impact, notched, 23°C	64	J/m	ASTM D256
Instrumented Dart Impact Energy @ peak, 23°C	8	J	ASTM D3763
Multiaxial Impact	2	J	ISO 6603
Izod Impact, unnotched 80*10*4 +23°C	29	kJ/m²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	8	kJ/m²	ISO 180/1A
THERMAL (1)			
HDT, 1.82 MPa, 3.2mm, unannealed	181	°C	ASTM D648
CTE, -40°C to 40°C, flow	3.06E-05	1/°C	ASTM E831

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CHEMISTRY THAT MATTERS"



PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
CTE, -40°C to 40°C, xflow	3.6E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, flow	3.1E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	3.66E-05	1/°C	ISO 11359-2
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	182	°C	ISO 75/Af
PHYSICAL (1)			
Density	1.483	g/cm³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.2	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.2	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.6	%	ASTM D955
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.22	%	ISO 294
Mold Shrinkage, xflow, 24 hrs (2)	0.58	%	ISO 294
Density	1.47	g/cm³	ISO 1183
Moisture Absorption (23°C / 50% RH)	0.3	%	ISO 62
INJECTION MOLDING (3)			
Drying Temperature	120 – 150	°C	
Drying Time	4	Hrs	
Maximum Moisture Content	0.05	%	
Melt Temperature	360 – 370	°C	
Front - Zone 3 Temperature	350 – 360	°C	
Middle - Zone 2 Temperature	340 – 350	°C	
Rear - Zone 1 Temperature	325 – 340	°C	
Mold Temperature	150	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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